



Bluetooth v4.0 Dual-Mode UART HCI Module

BT830 – Hardware Integration Guide (HIG)

Version 0.1 - PRELIMINARY

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REVISION HISTORY

Revision	Date	Changes
0.1	26 March 2014	Initial preliminary version

PRELIMINARY

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1 SCOPE

This document describes key hardware aspects of the Laird BT830 Bluetooth HCI module. This document is intended to assist device manufacturers and related parties with the integration of this module into their host devices. Data in this document are drawn from a number of sources including data sheets for the CSR8811.

Because the BT830 is currently in development stage, this document is preliminary and the information in this document is subject to change. Please contact Laird Technologies or visit the Laird website at www.Lairdtech.com to obtain the most recent version of this document.

2 OPERATIONAL DESCRIPTION

The BT830 series of UART HCI devices are designed to meet the needs of OEMs adding robust Bluetooth connectivity and using embedded Bluetooth stacks within these products.

Leveraging the market-leading CSR8811 chipset, the BT830 series provides exceptionally low power consumption with outstanding range. Supporting the latest Bluetooth v4.0 Specification with EDR (Enhanced Data Rate), the Laird BT830 series enables OEMs to accelerate their development time for leveraging either Classic Bluetooth or Bluetooth Low Energy (BLE) into their operating system based devices.



Figure 1: BT830 module

With a tiny footprint as small as 8.5 x 13 mm, yet output power at 7 dBm, these modules are ideal for applications where designers need high performance in minimal size. For maximum flexibility in systems integration, the modules are designed to support a UART interface plus GPIO and additionally I2S and PCM audio interfaces.

These modules present an HCI interface and have native support for Windows and Linux Bluetooth software stacks. All BT830 series devices are fully qualified as Bluetooth Hardware Controller Subsystem products. This also allows designers to integrate their existing pre-approved Bluetooth Host and Profile subsystem stacks to gain a Bluetooth END product approval for their products.

The BT830 series is engineered to provide excellent RF performance with integrated antenna and additional band pass filters. It further reduces regulatory and testing requirements for OEMs and ensures a hassle free development cycle.

A fully featured, low-cost developer's kit is available for prototyping, debug, and integration testing of the BT830 series modules and further reduces risk and time in development cycles.

2.1 Features & Benefits



- Bluetooth v4.0 - Dual mode (Classic Bluetooth and BLE)
- Compact footprint
- 2-wire and 3-wire Wi-Fi coexistence scheme
- High antenna radiation gain and efficiency
- Good interference rejection for multi-com system (GSM/WCDMA)
- Class 1 output – 7 dBm
- UART, GPIO, I2S, and PCM
- Industrial Temperature Range
- Bluetooth Hardware Controller subsystem
- FCC, IC and CE approvals

2.2 Application Areas

- Medical devices
- ePOS terminals
- Barcode scanners
- Industrial Cable Replacement
- M2M Connectivity
- Automotive Diagnostic Equipment
- Personal Digital Assistants (PDA)
- Bluetooth HID device (keyboard, mouse, and joystick)

3 BLOCK DIAGRAM AND DESCRIPTIONS

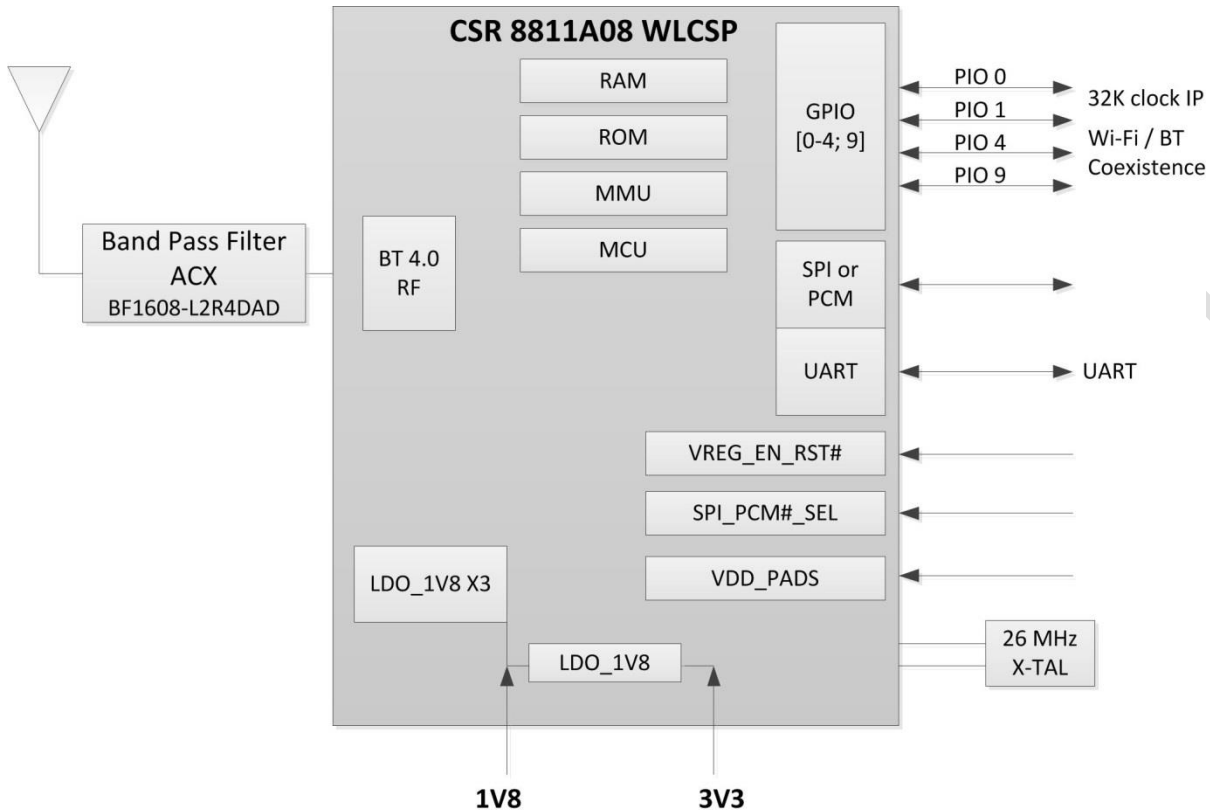


Figure 1: BT830 module block diagram

CS8811A08 (Main chip) The BT830 is based on CSR8811A08 dual mode chip. The chip is a single-chip radio with on-chip LDO regulators and baseband IC for Bluetooth 2.4 GHz systems including EDR to 3 Mbps. Dedicated signal and baseband processing is included for full Bluetooth operation. The chip provides PCM/I2S and UART interfaces. Up to four general purpose I/Os are available for general use such as Wi-Fi coexistence or general indicators.

Note: The purpose of the SPI interface is to access the module’s inner settings such as selecting different WLAN CO-EXIST scheme and enabling HID proxy mode. The SPI interface can also be used to put the module in RF test mode. You cannot use the module over the SPI interface for normal operation as the main host interface.

Antenna	The antenna is a ceramic monopole chip antenna.
Band Pass Filter	The band pass filter filters the out-of-band emissions from the transmitter to meet the specific regulations for type approvals of various countries.
Crystal	The embedded 26 MHz crystal is used for generating the clock for the entire module.

4 SPECIFICATIONS

Table 1: BT830 specifications

CATEGORIES	FEATURE	IMPLEMENTATION
Wireless Specification	Bluetooth®	V4.0 Dual Mode
	Frequency	2.402 - 2.480 GHz
	Maximum Transmit Power	Class 1 +7 dBm from antenna
	Receive Sensitivity	-89 dBm
	Range	Circa 100 meters
	Data Rates	Up to 3 Mbps (over the air)
	Host Interface	UART
GPIO		Four configurable lines (1.8V/3.3V configurable by VDD_PADS)
Operational Modes	HCI	Host Controller Interface over UART
Coexistence	802.11 (Wi-Fi)	3 wire CSR schemes supported (Unity-3;Unity-3e, and Unity+)
Supply Voltage	Supply	3.3V +/-10% Note: See Implementation Note for details on different DC power selections on the BT830.
Power Consumption	Current	Idle Mode ~TBD mA (Master; ACL link; No traffic) File Transfer ~TBD mA (Master; ACL link; Transmit)
Antenna Option	Internal	Multilayer ceramic antenna with up to 41% efficiency.
Physical	Dimensions	8.5 x 13 x 1.6 mm (BT830 - Module)
Environmental	Operating	-30C to +85C
	Storage	-40C to +85C
Miscellaneous	Lead Free	Lead-free and RoHS compliant
	Warranty	1 Year
Approvals	Bluetooth®	Hardware Controller Subsystem Approved
	FCC / IC / CE	All BT830 series (BT830-SA; BT830-ST)

5 PIN DEFINITIONS

Table 2: BT830 pin definitions

#	Pin Name	I/O	Supply Domain	Description
1	VDD_PADS	Power supply	(1.7V-3.6V)	Positive supply for digital I/O pads
2	GND	GND	-	Ground
3	UART_RTS	Bidirectional, tristate, with weak internal pullup	VDD_PADS	UART data output, active high
4	UART_TX	Bidirectional, tristate, with weak internal pullup	VDD_PADS	UART data input, active high
5	UART_CTS	Bidirectional, tristate, with weak internal pullup	VDD_PADS	UART clear to send, active low
6	UART_RX	Bidirectional, tristate, with weak internal pullup	VDD_PADS	UART request to send, active low
7	GND	GND	-	Ground
8	VREG_EN_RST#	Input with strong internal pull-down	VDD_PADS	Take high to enable internal regulators. Also acts as active low reset. Maximum voltage is VDD_PADS.
9	VREG_IN_HV	Analogue regulator input	3.3V	Input to internal high-voltage regulator
10	VREG_OUT_HV	Analogue regulator input/output	1.8V	Output from internal high-voltage regulator and input to low-voltage internal regulators.
11	GND	GND	-	Ground
12	GND	GND	-	Ground
13	GND	GND	-	Ground
14	GND	GND	-	Ground
15	GND	GND	-	Ground
16	GND	GND	-	Ground
17	RF			RF signal out (50 ohm) for BT830-ST version only. Not connection for BT830-SA.
18	GND	GND	-	Ground
19	PCM_SYNC/ SPI_CS#/ PIO23	Bidirectional, tri-state, with weak internal pull-down	VDD_PADS	PCM synchronous data sync SPI chip select, active low Programmable input/output line *See Note 1 .

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#	Pin Name	I/O	Supply Domain	Description
20	PCM_CLK/ SPI_CLK/ PIO24	Bidirectional, tri-state, with weak internal pull-down	VDD_PADS	PCM synchronous data clock SPI clock Programmable input/output line *See Note 1 .
21	PCM_IN/ SPI_MOSI/ PIO21	Input, tri-state, with weak internal pull- down	VDD_PADS	PCM synchronous data input SPI data input Programmable input/output line *See Note 1 .
22	PCM_OUT/ SPL_MISO/ PIO22	Output, tri-state, with weak internal pull- down	VDD_PADS	PCM synchronous data output SPI data output Programmable input/output line *See Note 1 .
23	GND	GND	-	Ground
24	PIO0/ 32K_CLK_IN	Bidirectional, tri-state, with weak internal pull- down	VDD_PADS	Programmable input/output line and 32kHz sleep clock input
25	PIO1/ BT_ACTIVE	Bidirectional, tri-state, with weak internal pull- down	VDD_PADS	Programmable input/output line; Wi-Fi & BT 3-wire coexistence
26	PIO9/ BT_PRIORITY	Bidirectional, tri-state, with weak internal pull- down	VDD_PADS	Programmable input/output line; Wi-Fi & BT 3-wire coexistence
27	PIO4/ WLAN_ACTIVE	Bidirectional, tri-state, with weak internal pull- down	VDD_PADS	Programmable input/output line; Wi-Fi & BT 3-wire coexistence
28	SPI_PCM#_SEL	Input with weak internal pull-down	VDD_PADS	Control line to select SPI or PCM interface, high = SPI, low = PCM *See Note 1 .
29	GND	GND	-	Ground
30	GND	GND	-	Ground

Note 1: The purpose of the SPI interface is to access the module's inner settings such as selecting different WLAN CO-EXIST scheme. The SPI interface can also be used to put the module in RF test mode. You cannot use the module over the SPI interface for normal operation as the main host interface.

6 DC ELECTRICAL CHARACTERISTIC

Table 3: Absolute maximum ratings

Rating	Min	Max	Unit
Storage temperature	-40	+85	°C
VREG_IN_HV	2.3	4.8	V
VREG_OUT_HV	1.7	2.0	V
VDD_PADS	-0.4	3.6	V
Other terminal voltages	VSS - 0.4V	VDD + 0.4 V	V

Table 4: Recommended operating conditions

Rating	Min	Max	Unit
Operating temperature	-30	+85	°C
VREG_IN_HV	2.3	4.8	V
VREG_OUT_HV	1.75	1.95	V
VDD_PADS	1.2	3.6	V
VREG_EN_RST#	VDD_PADS	VDD_PADS	V

Table 5: High-voltage Linear Regulator

Normal Operation	Min	Typ	Max	Unit
Input voltage (VREG_IN_HV)	3.1	3.3	3.6	V
Output voltage (VREG_OUT_HV)	1.75	1.85	1.95	V
Temperature coefficient	-200	-	200	ppm/°C
Output noise (frequency range 100Hz to 100kHz)	-	-	0.4	mV rms
Settling time (settling time within 10% of final value)	-	-	5	µs
Output current	-	-	100	mA
Quiescent current (excluding load, load <1mA)	30	40	60	µA
Low-power Mode				
Quiescent current (excluding load, load <100µA)	14	18	23	µA

Table 6: Digital I/O Characteristics

Normal Operation	Min	Typ	Max	Unit
Input Voltage				
VIL input logic level low	-0.4	-	0.4	V
VIH input logic level high	0.7 x VDD	-	VDD + 0.4	V

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Normal Operation	Min	Typ	Max	Unit
Output Voltage				
VOL output logic level low, IOL = 4.0 mA	-	-	0.4	V
VOH output logic level high, IOL = 4.0 mA	0.75 x VDD	-	-	V
Input and Tristate Currents				
Strong pull-up	-150	-40	-10	μA
Strong pull-down	10	40	150	μA
Weak pull-up	-5	-1.0	-0.33	μA
Weak pull-down	0.33	1.0	5.0	μA
CI input capacitance	1.0	-	5.0	pF

Table 7: Current Consumption

Normal Operation	Peak (7 dBm)	AVG	Unit
Idle		4.3	mA
Inquiry		891	μA
File Transfer	73	58	mA
LE Connected (Master)	74		mA
LE Scan (Master)	48		mA

7 RF CHARACTERISTICS

Table 8: Receiver Characteristics

RF Characteristics, VDD = 3.3V @ room temperature unless otherwise specified		Min	Typ.	Max	BT. Spec.	Unit
Maximum RF Transmit Power			7	8	20	dBm
RF power variation over temperature range			1.5		-	dB
RF power variation over supply voltage range				0.2	-	dB
RF power variation over BT band			2		-	dB
RF power control range		-21		8	-	dBm
20 dB band width for modulated carrier					1000	kHz
ACP	F = F ₀ ± 2MHz				-20	
	F = F ₀ ± 3MHz				-40	
	F = F ₀ > 3MHz				-40	
Drift rate			10		+/-25	kHz
ΔF _{1avg}			165		140<175	kHz
ΔF _{1max}			168		140<175	kHz
ΔF _{2avg} / ΔF _{1avg}			0.9		>=0.8	

Table 9: BDR and EDR receiver sensitivity

RF Characteristics, VDD = 3.3V @ room temp.	Packet Type	Min	Typ	Max	BT. Spec.	Unit
Sensitivity for 0.1% BER	DH1		-89		-70	dBm
	DH3		-89			dBm
	DH5		-89			dBm
	2-DH5		-92			dBm
	3-DH5		-85			dBm
Sensitivity variation over BT band	All		2			dB
Sensitivity variation over temperature range	All		TBD			dB

8 INTERFACE

8.1 PIO

See the Device Terminal Functions section for the list of supplies to the PIOs (Programmable I/O ports).

PIO lines are configured through software to have either weak or strong pull-ups or pull-downs. All PIO lines are configured as inputs with weak pull-downs at reset and have additional individual bus-keeper configuration.

8.2 WLAN Coexistence Interface

Dedicated hardware is provided to implement a variety of WLAN coexistence schemes. There is support for:

- Channel skipping AFH
- Priority signaling
- Channel signaling
- Host passing of channel instructions

The BT830 supports the WLAN coexistence schemes:

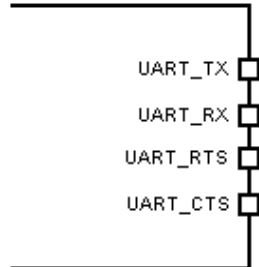
- Unity-3
- Unity-3e
- Unity+

For more information see [BT830 WLAN Coexistence Schemes and LED Indication](#).

8.3 UART Interface

This is a standard UART interface for communicating with other serial devices.

CSR8811 UART interface provides a simple mechanism for communicating with other serial devices using the RS-232 protocol.



The above figure shows the 4 signals that implement the UART function. When BT830 is connected to another digital device, UART_RX and UART_TX transfer data between the 2 devices. The remaining 2 signals, UART_CTS and UART_RTS, implement RS232 hardware flow control where both are active low indicators. The default configuration of UART is 115200 bauds; None parity check; 1 stop bit; 8 bits per byte.

Note: To communicate with the UART at its maximum data rate using a standard PC, an accelerated serial port adapter card is required for the PC.

8.4 PCM Interface

The audio PCM interface on the BT830 supports:

- Continuous transmission and reception of PCM encoded audio data over Bluetooth.
- Processor overhead reduction through hardware support for continual transmission and reception of PCM data.
- A bidirectional digital audio interface that routes directly into the baseband layer of the firmware. It does not pass through the HCI protocol layer.
- Hardware on the BT830 for sending data to and from a SCO connection.
- Up to three SCO connections on the PCM interface at any one time.
- PCM interface master, generating PCM_SYNC and PCM_CLK.
- PCM interface slave, accepting externally generated PCM_SYNC and PCM_CLK.
- Various clock formats including:
 - Long Frame Sync
 - Short Frame Sync
- GCI timing environments.
- 13-bit or 16-bit linear, 8-bit μ -law, or A-law companded sample formats.
- Receives and transmits on any selection of three of the first four slots following PCM_SYNC.

The PCM configuration options are enabled by setting PSKEY_PCM_CONFIG32.

8.4.1 PCM Interface Master/Slave

When configured as the master of the PCM interface, the BT830 generates PCM_CLK and PCM_SYNC.

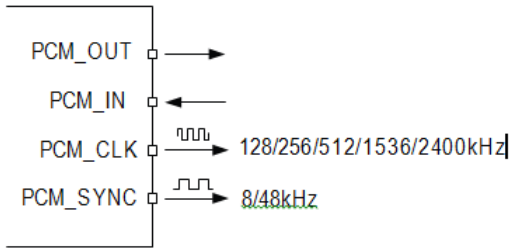


Figure 2: PCM Interface Master

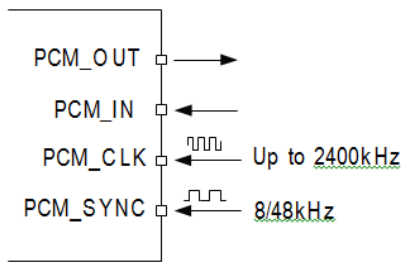


Figure 3: PCM Interface Slave

8.4.2 Long Frame Sync

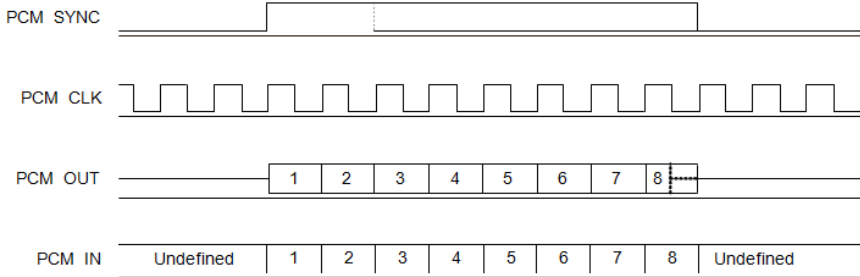


Figure 4: Long Frame Sync (shown with 8-bit Companded Sample)

Long Frame Sync is the name given to a clocking format that controls the transfer of PCM data words or samples. In Long Frame Sync, the rising edge of PCM_SYNC indicates the start of the PCM word. When the BT830 is configured as PCM master, generating PCM_SYNC and PCM_CLK, then PCM_SYNC is eight bits long. When the BT830 is configured as PCM Slave, PCM_SYNC is from one cycle PCM_CLK to half the PCM_SYNC rate.

BT830 samples PCM_IN on the falling edge of PCM_CLK and transmits PCM_OUT on the rising edge. PCM_OUT is configurable as high impedance on the falling edge of PCM_CLK in the LSB position or on the rising edge.

8.4.3 Short Frame Sync

In Short Frame Sync, the falling edge of PCM_SYNC indicates the start of the PCM word. PCM_SYNC is always one clock cycle long.

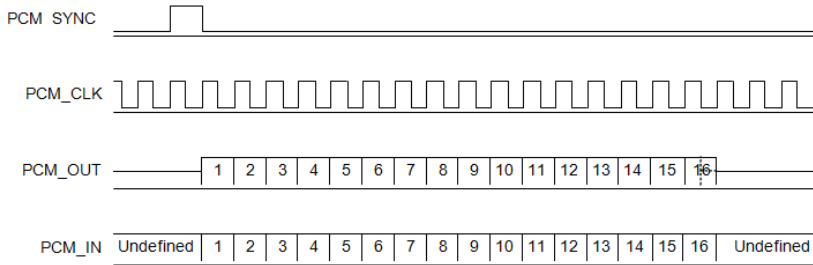


Figure 5: Short Frame Sync (Shown with 16-bit Sample)

As with Long Frame Sync, BT830 samples PCM_IN on the falling edge of PCM_CLK and transmits PCM_OUT on the rising edge. PCM_OUT is configurable as high impedance on the falling edge of PCM_CLK in the LSB position or on the rising edge.

8.4.4 Multi-Slot Operation

More than 1 SCO connection over the PCM interface is supported using multiple slots. Up to 3 SCO connections are carried over any of the first 4 slots.

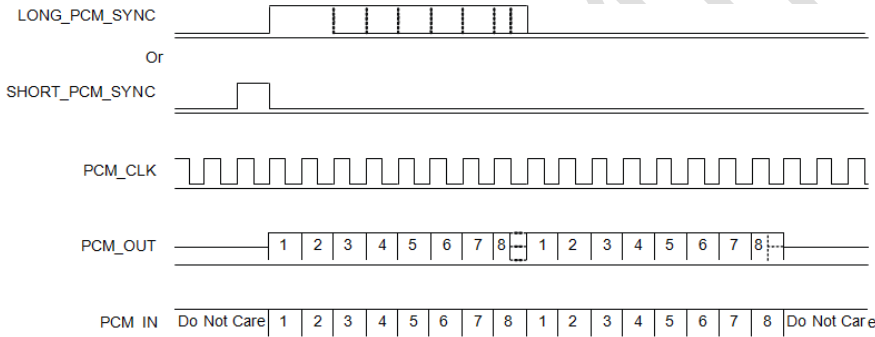


Figure 6: Multi-slot Operation with 2 Slots and 8-bit Companded Samples

8.5 GCI Interface

BT830 is compatible with the GCI, a standard synchronous 2B+D ISDN timing interface. The two 64 kbps B channels are accessed when this mode is configured.

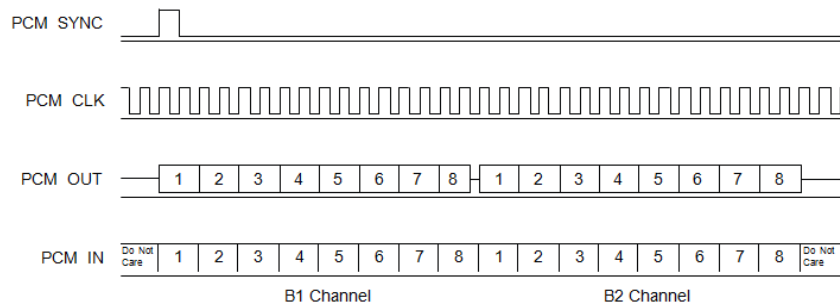


Figure 7: Multi-slot Operation

The start of frame is indicated by the rising edge of PCM_SYNC and runs at 8 kHz.

8.6 Slots and Sample Formats

BT830 receives and transmits on any selection of the first four slots following each sync pulse. Slot durations are either 8 or 16 clock cycles:

- 8 clock cycles for 8-bit sample formats.
- 16 clock cycles for 8-bit, 13-bit, or 16-bit sample formats.

BT830 supports:

- 13-bit linear, 16-bit linear and 8-bit μ -law or A-law sample formats
- A sample rate of 8 kbps
- Little or big endian bit order
- For 16-bit slots, the three or eight unused bits in each slot are filled with sign extension, padded with zeros or a programmable 3-bit audio attenuation compatible with some codecs.

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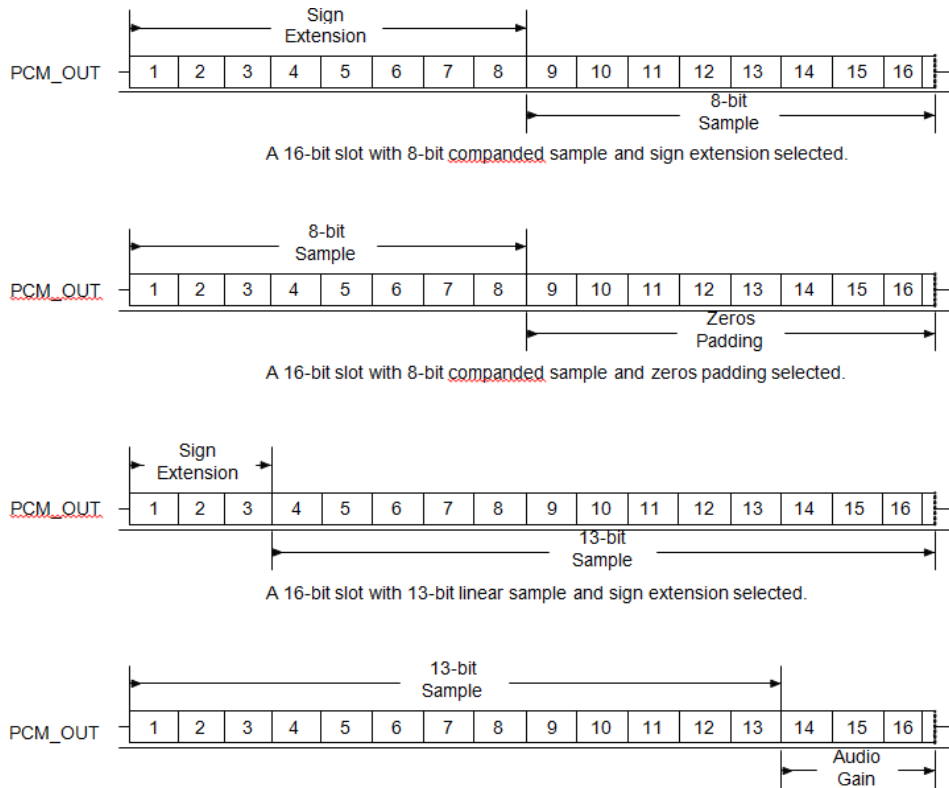


Figure 8: 16-bit Slot Length and Sample Formats

8.7 PCM Timing Information

Table 10: PCM Timing information

Symbol	Parameter	Min	Typ	Max	Unit
f_{mclk}	PCM_CLK frequency	-	128	-	kHz
			256		
			512		
		4MHz DDS generation. Frequency selection is programmable.	2.9	-	kHz
-	PCM_SYNC frequency for SCO connection	-	8	-	kHz
t_{mclkh} (a)	PCM_CLK high	4MHz DDS generation	980	-	ns
t_{mckl} (a)	PCM_CLK low	4MHz DDS generation	730	-	ns
-	PCM_CLK jitter	48MHz DDS generation	-	21	ns pk-pk
$t_{dmcklsynch}$	Delay time from PCM_CLK high to PCM_SYNC high	4MHz DDS generation	-	20	ns
		48MHz DDS generation	-	40.83	ns
$t_{dmcklpout}$	Delay time from PCM_CLK high to valid PCM_OUT	-	-	20	ns
$t_{dmcklsyncl}$	Delay time from PCM_CLK low to	4MHz DDS generation	-	20	ns
		48MHz DDS generation	-	40.83	ns

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Symbol	Parameter	Min	Typ	Max	Unit
	PCM_SYNC low (long frame sync only)				

(a) Assumes normal system clock operation. Figures vary during low-power modes, when system clock speeds are reduced.

Table 11: PCM Master Mode Timing Parameters

Symbol	Parameter	Min	Typ	Max	Unit	
$t_{dmclkhsync}$	Delay time from PCM_CLK high to PCM_SYNC low	4MHz DDS generation	-	-	20	ns
		48MHz DDS generation	-	-	40.83	ns
$t_{dmclkpoutz}$	Delay time from PCM_CLK low to PCM_OUT high impedance	-	-	20	ns	
$t_{dmclkhoutz}$	Delay time from PCM_CLK high to PCM_OUT high impedance	-	-	20	ns	
$t_{suninckl}$	Set-up time for PCM_IN valid to PCM_CLK low	20	-	-	ns	
$t_{hpinckl}$	Hold time for PCM_CLK low to PCM_IN invalid	0	-	-	ns	

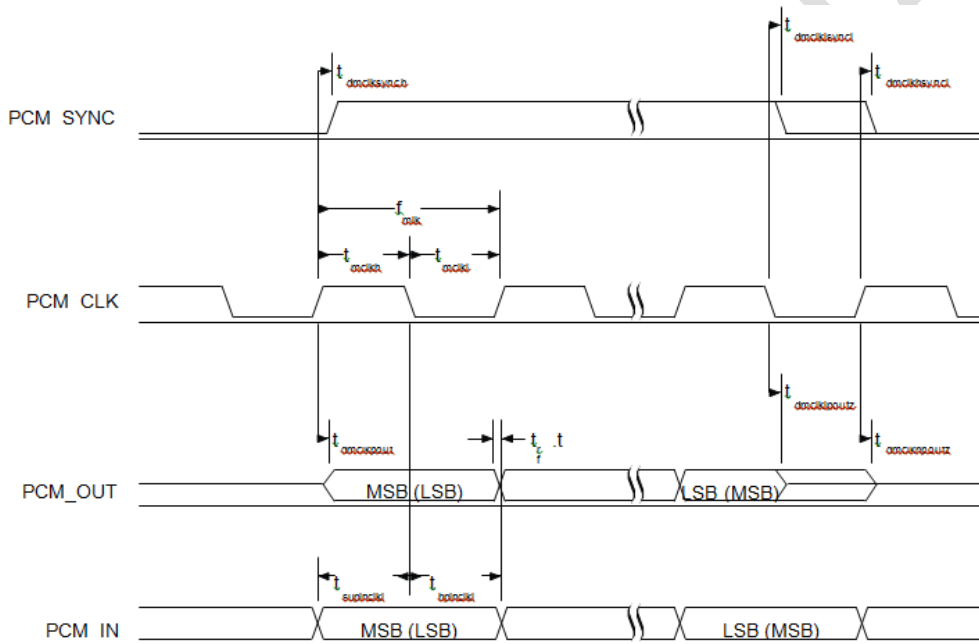


Figure 9: PCM Master Timing Long Frame Sync

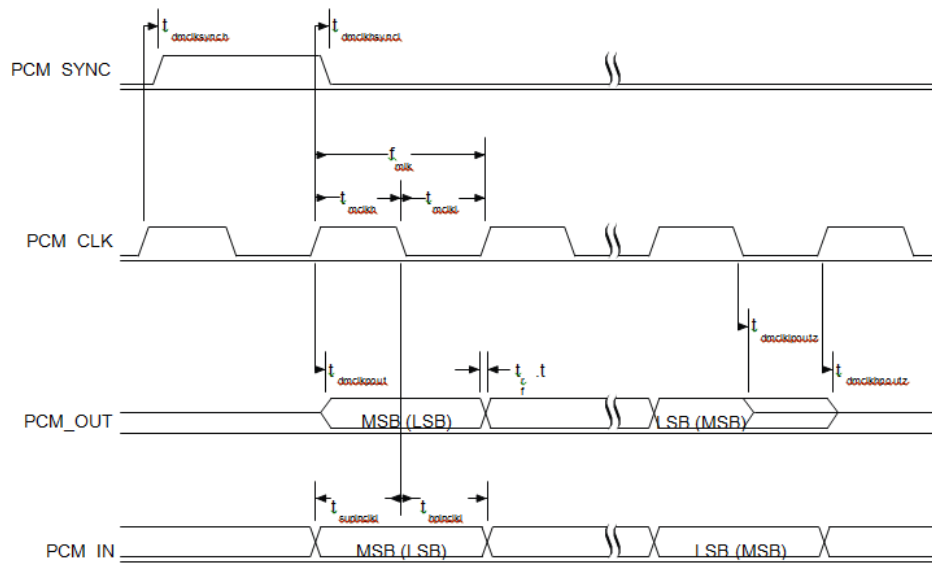


Figure 10: PCM Master Timing Short Frame Sync

8.8 PCM Slave Timing

Symbol	Parameter	Min	Typ	Max	Unit
f_{sclk}	PCM clock frequency (Slave mode: input)	64	-	2048	kHz
f_{sclk}	PCM clock frequency (GCI mode)	128	-	4096	kHz
t_{sckl}	PCM_CLK low time	200	-	-	ns
t_{sclkh}	PCM_CLK high time	200	-	-	ns

8.9 PCM Slave Mode Timing Parameters

Symbol	Parameter	Min	Typ	Max	Unit
$t_{hsclksynch}$	Hold time from PCM_CLK low to PCM_SYNC high	2	-	-	ns
$t_{susclksynch}$	Set-up time for PCM_SYNC high to PCM_CLK low	20	-	-	ns
t_{dpout}	Delay time from PCM_SYNC or PCM_CLK, whichever is later, to valid PCM_OUT data (long frame sync only)	-	-	15	ns
$t_{dsclkhout}$	Delay time from CLK high to PCM_OUT valid data	-	-	15	ns
t_{dpoutz}	Delay time from PCM_SYNC or PCM_CLK low, whichever is later, to PCM_OUT data line high impedance	-	-	20	ns
$t_{supinsckl}$	Set-up time for PCM_IN valid to CLK low	20	-	-	ns
$t_{hpinsckl}$	Hold time for PCM_CLK low to PCM_IN invalid	2	-	-	ns

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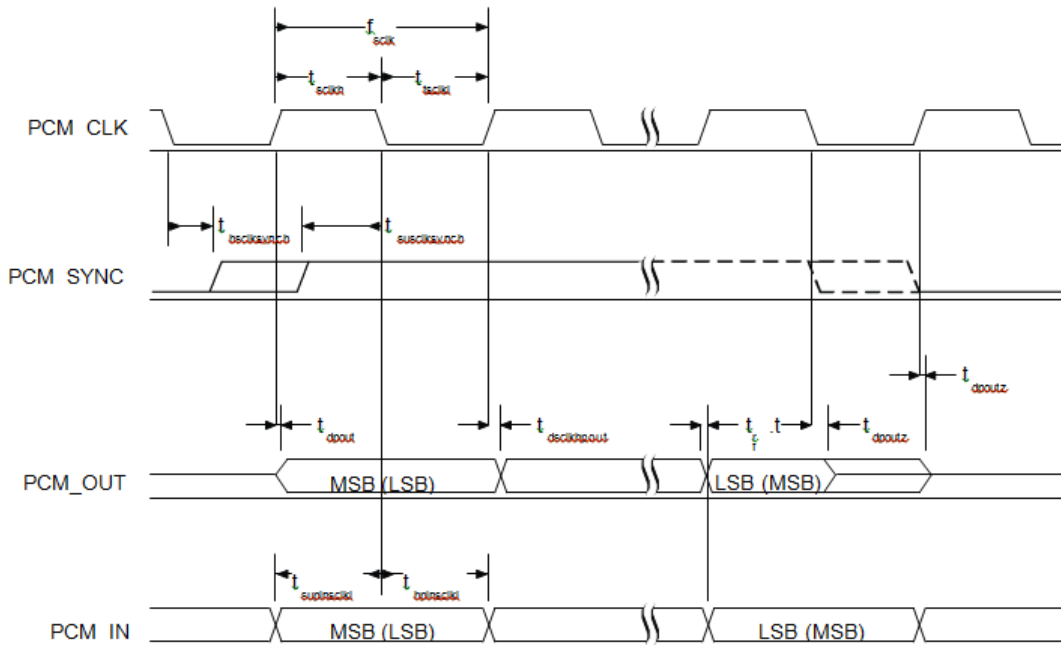


Figure 11: PCM Slave Timing Long Frame Sync

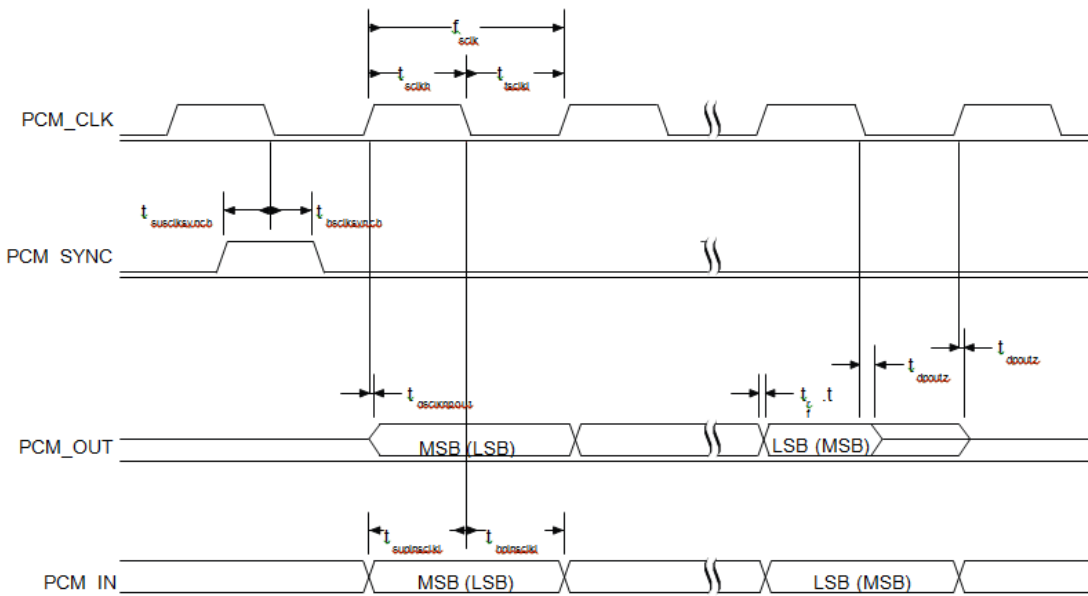


Figure 12: PCM Slave Timing Short Frame Sync

8.10 PCM_CLK and PCM_SYNC Generation

BT830 has two methods of generating PCM_CLK and PCM_SYNC in master mode:

- Generating these signals by DDS from BT830 internal 4MHz clock. Using this mode limits PCM_CLK to 128, 256 or 512 kHz and PCM_SYNC to 8 kHz.
- Generating these signals by DDS from an internal 48MHz clock, which enables a greater range of frequencies to be generated with low jitter but consumes more power. To select this second method set bit 48M_PCM_CLK_GEN_EN in PSKEY_PCM_CONFIG32. When in this mode and with long frame sync, the length of PCM_SYNC is either 8 or 16 cycles of PCM_CLK, determined by LONG_LENGTH_SYNC_EN in PSKEY_PCM_CONFIG32.

Equation 8.1 describes PCM_CLK frequency when generated from the internal 48MHz clock:

$$f = \frac{\text{CNT_RATE}}{\text{CNT_LIMIT}} \times 24\text{MHz}$$

Equation 8.1: PCM_CLK Frequency Generated Using the Internal 48MHz Clock

Set the frequency of PCM_SYNC relative to PCM_CLK using Equation 8.2:

$$f = \frac{\text{PCM_CLK}}{\text{SYNC_LIMIT} \times 8}$$

Equation 8.2: PCM_SYNC Frequency Relative to PCM_CLK

CNT_RATE, CNT_LIMIT and SYNC_LIMIT are set using PSKEY_PCM_LOW_JITTER_CONFIG. As an example, to generate PCM_CLK at 512kHz with PCM_SYNC at 8kHz, set SKEY_PCM_LOW_JITTER_CONFIG to 0x08080177.

8.11 PCM Configuration

Configure the PCM by using PSKEY_PCM_CONFIG32 and PSKEY_PCM_LOW_JITTER_CONFIG (See your PSKey file). The default for PSKEY_PCM_CONFIG32 is 0x00800000 (for example: first slot following sync is active, 13-bit linear voice format, long frame sync and interface master generating 256kHz PCM_CLK from 4MHz internal clock with no tri-state of PCM_OUT).

8.12 Digital Audio Interface (I²S)

The digital audio interface supports the industry standard formats for I²S, left-justified or right-justified. The interface shares the same pins as the PCM interface, which means each audio bus is mutually exclusive in its usage. Table 12 lists these alternative functions. Figure 11 shows the timing diagram.

Table 12: Alternative Functions of the Digital Audio Bus Interface on the PCM Interface.

PCM Interface	I ² S Interface
PCM_OUT	SD_OUT
PCM_IN	SD_IN
PCM_SYNC	WS
PCM_CLK	SCK

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Configure the digital audio interface using PSKEY_DIGITAL_AUDIO_CONFIG, see BlueCore Audio API Specification and the PS Key file.

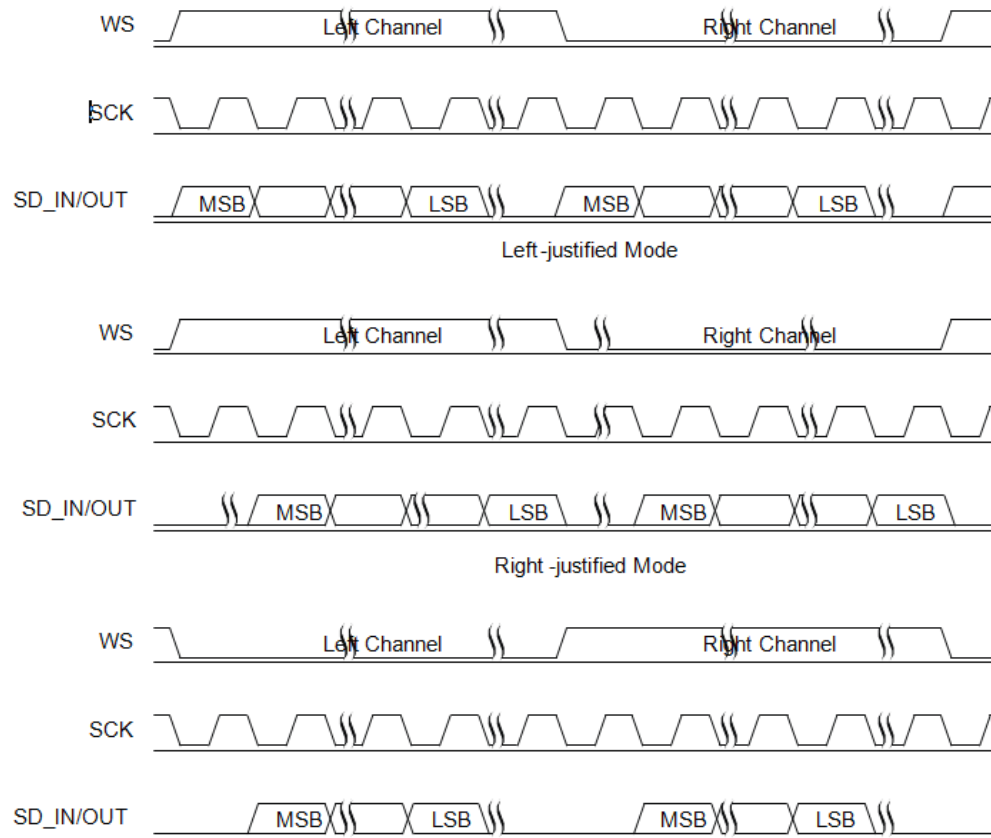


Figure 13: PCM Configuration

The internal representation of audio samples within BT830 is 16-bit and data on SD_OUT is limited to 16-bit per channel.

Table 13: Digital Audio Interface Slave Timing

Symbol	Parameter	Min	Typ	Max	Unit
-	SCK Frequency	-	-	6.2	MHz
-	WS Frequency	-	-	96	kHz
t_{ch}	SCK high time	80	-	-	ns
t_{cl}	SCK low time	80	-	-	ns

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Table 14: I²S Slave Mode Timing

Symbol	Parameter	Min	Typ	Max	Unit
t_{ssu}	WS valid to SCK high set-up time	20	-	-	ns
t_{sh}	SCK high to WS invalid hold time	2.5	-	-	ns
t_{ond}	SCK low to SD_OUT valid delay time	-	-	20	ns
t_{isu}	SD_IN valid to SCK high set-up time	20	-	-	ns
t_{ih}	SCK high to SD_IN invalid hold time	2.5	-	-	ns

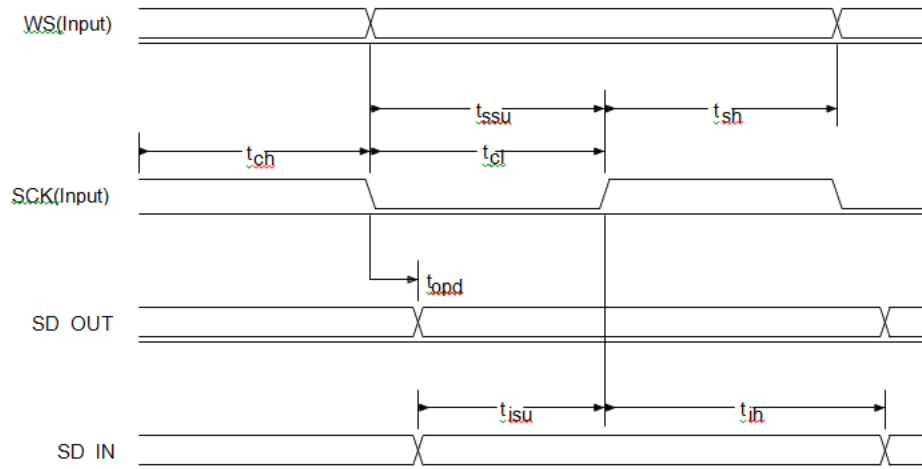


Figure 14: Digital Audio Interface Slave Timing

Table 15: Digital Audio Interface Master Timing

Symbol	Parameter	Min	Typ	Max	Unit
-	SCK Frequency	-	-	6.2	MHz
-	WS Frequency	-	-	96	kHz

Table 16: I²S Master Mode Timing Parameters, WS and SCK as Outputs

Symbol	Parameter	Min	Typ	Max	Unit
t_{sod}	SCK low to WS valid delay time	-	-	39.27	ns
t_{ond}	SCK low to SD_OUT valid delay time	-	-	18.44	ns
t_{isu}	SD_IN valid to SCK high set-up time	18.44	-	-	ns
t_{ih}	SCK high to SD_IN invalid hold time	0	-	-	ns

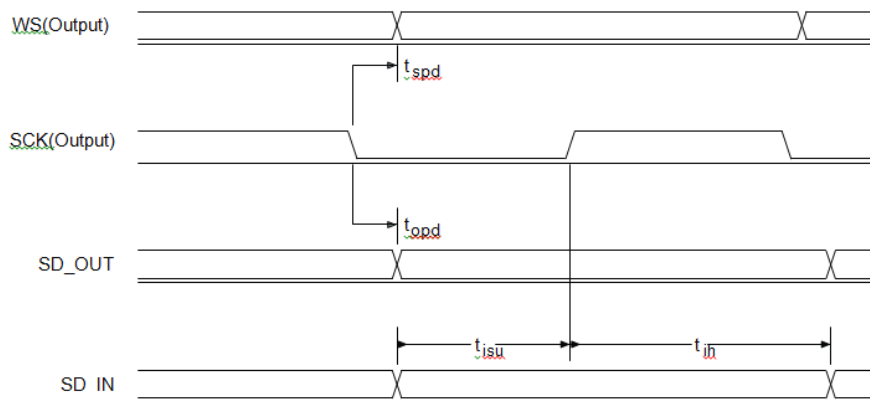


Figure 15: Digital Audio Interface Master Timing

9 POWER SUPPLY AND REGULATION

See the Example Application Schematic (**Error! Reference source not found.**) for the regulator configuration. BT830 can be powered by either two sources listed below

- Method #1:** Apply 3.3 V on pin-9, High-voltage linear regulator input (VREG_IN_HV), to generate the main 1.8 V out put on pin-10 (VREG_OUT_HV).
 A minimum 1.5 μ F capacitor must be connected to the Pin-10 (VREG_OUT_HV). Low ESR capacitors such as multilayer ceramic types should be used.
- Method #2:** Apply 1.8V on pin-10 High-voltage linear regulator output (VREG_OUT_HV), to generate the internal voltage for the system. Be sure to left Pin-9 un-connected in this method.

9.1 Voltage Regulator Enable and Reset

A single pin, VREG_EN_RST#, controls both the High-voltage linear regulator enables and the digital reset function. The VREG_EN_RST# pin remains active controlling the reset function if the HV linear regulator is not used so the pin must be driven high to take the device out of reset.

The regulator is enabled by taking the VREG_EN_RST# pin above 1V. The regulator can also be controlled by the software.

The VREG_EN_RST# is also connected internally to the reset function, and is powered from the VDD_PADS supply, so voltages above VDD_PADS must not be applied to this pin. The VREG_EN_RST# pin is pulled down internally.

The VREG_EN_RST# pin is an active low reset. Assert the reset signal for a period >5 ms to ensure a full reset.

Note: The regulator enables are released as soon as VREG_EN_RST# is low, so the regulators shut down. Therefore do not take VREG_EN_RST# low for less than 5 ms, as a full reset is not guaranteed.

Other reset sources are:

Power-on reset

Via a software-configured watchdog timer

A warm reset function is also available under software control. After a warm reset the RAM data remains available.

9.2 Power Sequencing

CSR recommends that all power supplies are powered at the same time. The order of powering the supplies relative to the I/O supply, VDD_PADS to VREG_IN_HV or VREG_OUT_HV, is not important.

10 ANTENNA PERFORMANCE

Table 17 displays antenna performance for this module.

Table 17: Gain table

Unit in dBi @ 2.44 GHz	XY-plane		XZ-plane		YZ-plane		Efficiency
	Peak	Avg.	Peak	Avg.	Peak	Avg.	
A1	-3.5	-4.2	3.8	-5.3	3.2	-4.7	41.0%

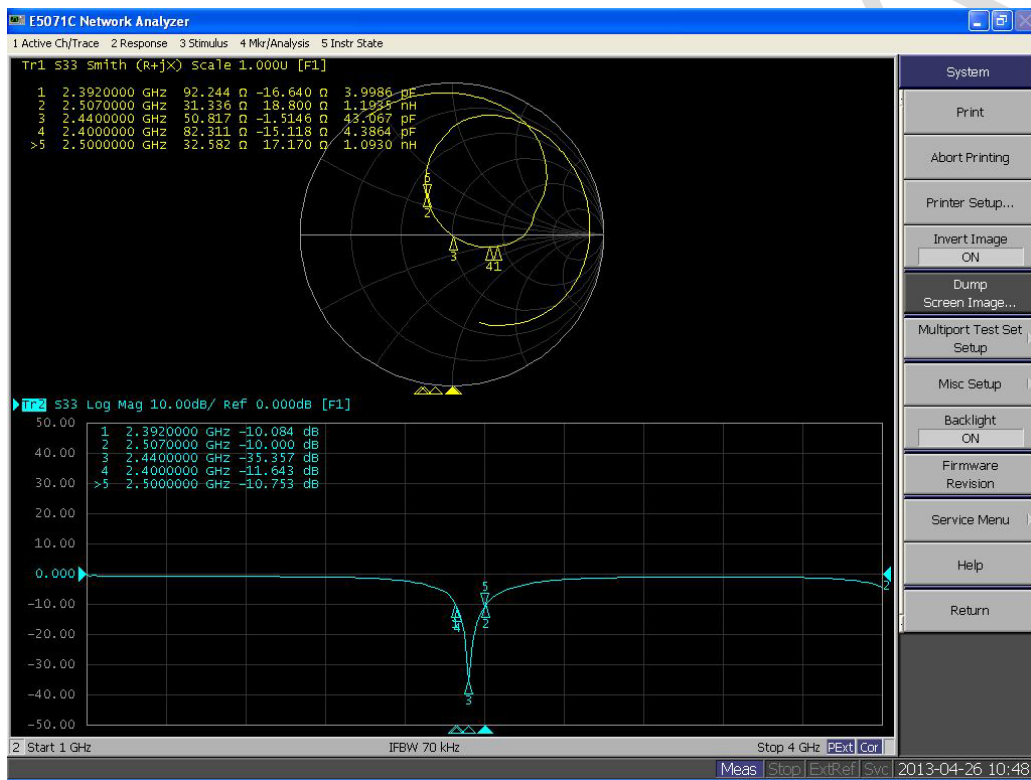
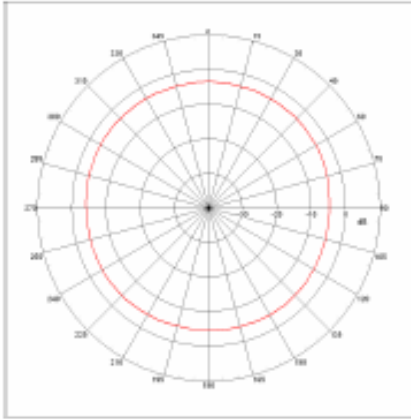


Figure 16: Network Analyzer output

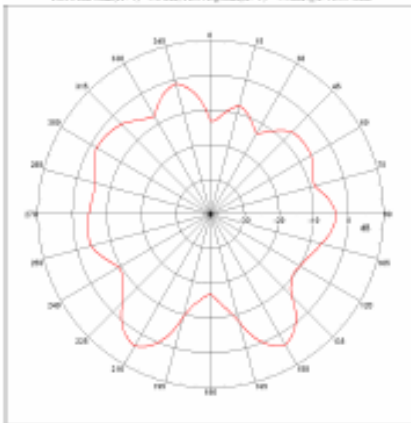
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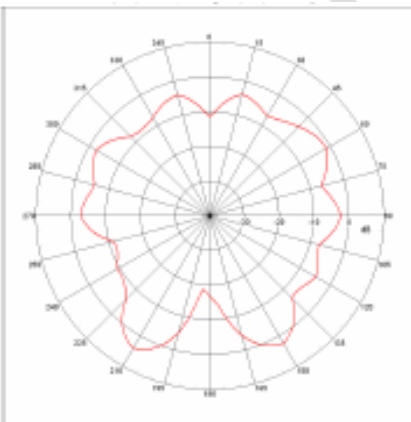
XY-plane	Peak	Avg.
	-3.5	-4.2

Figure 17: XY plane



XZ-plane	Peak	Avg.
	3.8	-5.3

Figure 18: XZ-plane

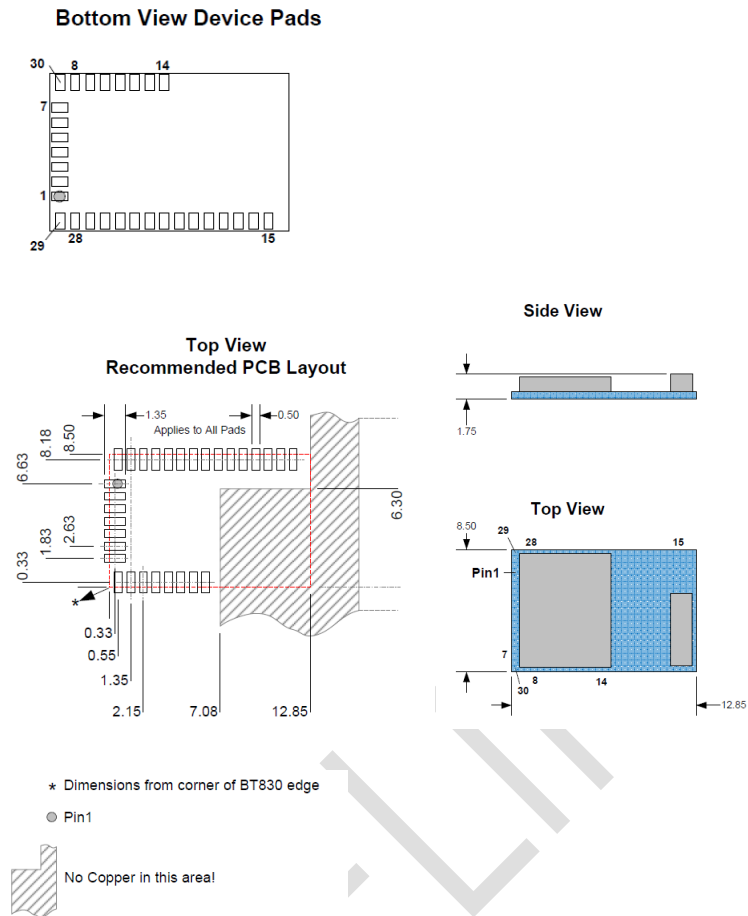


YZ-plane	Peak	Avg.
	3.2	-4.7

Figure 19: YZ-plane

11 MECHANICAL DIMENSIONS AND LAND PATTERN

11.1 BT830 Mechanical Drawing



Note: Dimensions are in mm.
 Tolerances: .xx ±0.03 mm
 .x ±1.3 mm

12 IMPLEMENTATION NOTE

12.1 PCB Layout on Host PCB

Checklist (for PCB):

- **MUST** locate the BT830 module close to the edge of PCB.
- Use solid GND plane on inner layer (for best EMC and RF performance).
- Place GND vias close to module GND pads as possible
- Route traces to avoid noise being picked up on VCC supply.
- Antenna Keep-out area:
 - Ensure there is no copper in the antenna keep-out area on any layers of the host PCB.
 - Keep all mounting hardware and metal clear of the area to allow proper antenna radiation.
 - For best antenna performance, place the BT830 module on the edge of the host PCB, preferably in the corner with the antenna facing the corner.
 - A different host PCB thickness dielectric will have small effect on antenna.

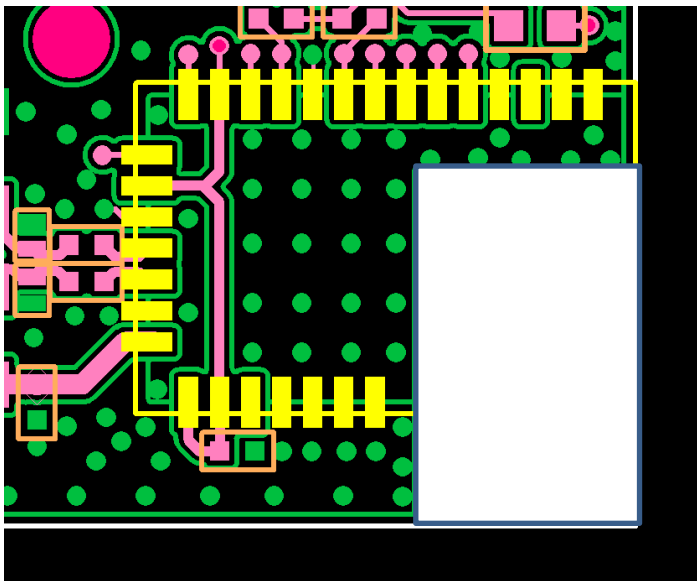


Figure 20: Recommend Antenna keep-out area (in White) used on the BT830

12.1.1 Antenna Keep-out and Proximity to Metal or Plastic

Checklist (for metal /plastic enclosure):

- Minimum safe distance for metals without seriously compromising the antenna (tuning) is 40 mm top/bottom and 30 mm left or right.
- Metal close to the BT830 chip monopole antenna (bottom, top, left, right, any direction) will have degradation on the antenna performance. The amount of degradation is entirely system dependent which means some testing by customers is required (in their host application).
- Any metal closer than 20 mm starts to significantly degrade performance (S11, gain, radiation efficiency).
- It is best that the customer tests the range with mock-up (or actual prototype) of the product to assess effects of enclosure height (and material whether metal or plastic).

12.1.2 DC power supply options for using BT830 module

- **Using DC power 3.3 V**
Power the on Pin-9 (VREG_IN_HV) with 3.3 V and pull-high on Pin-8 (VREG_EN_RST#) to turn on the internal regulator. The BT830 module generates 1.8 V output on Pin-10 (VREG_OUT_HV) which can supply to the other DC pin of the board.
- **Using DC power 1.8 V**
Leave the Pin-9 (VREG_IN_HV) no connection, power the Pin-10 (VREG_OUT_HV) with 1.8 V and pull-high on Pin-8 (VREG_EN_RST#) to turn on the internal regulator.

13 APPLICATION NOTE FOR SURFACE MOUNT MODULES

13.1 Introduction

Laird surface mount modules are designed to conform to all major manufacturing guidelines. This application note is intended to provide additional guidance beyond the information that is presented in the user manual. This application note is considered a living document and is updated as new information is presented.

The modules are designed to meet the needs of a number of commercial and industrial applications. They are easy to manufacture and they conform to current automated manufacturing processes.

13.2 Shipping tray

Modules are shipped in ESD (Electrostatic Discharge) safe trays that can be loaded into most manufacturers pick and place machines. Layouts of the trays are provided in [Figure 21](#).

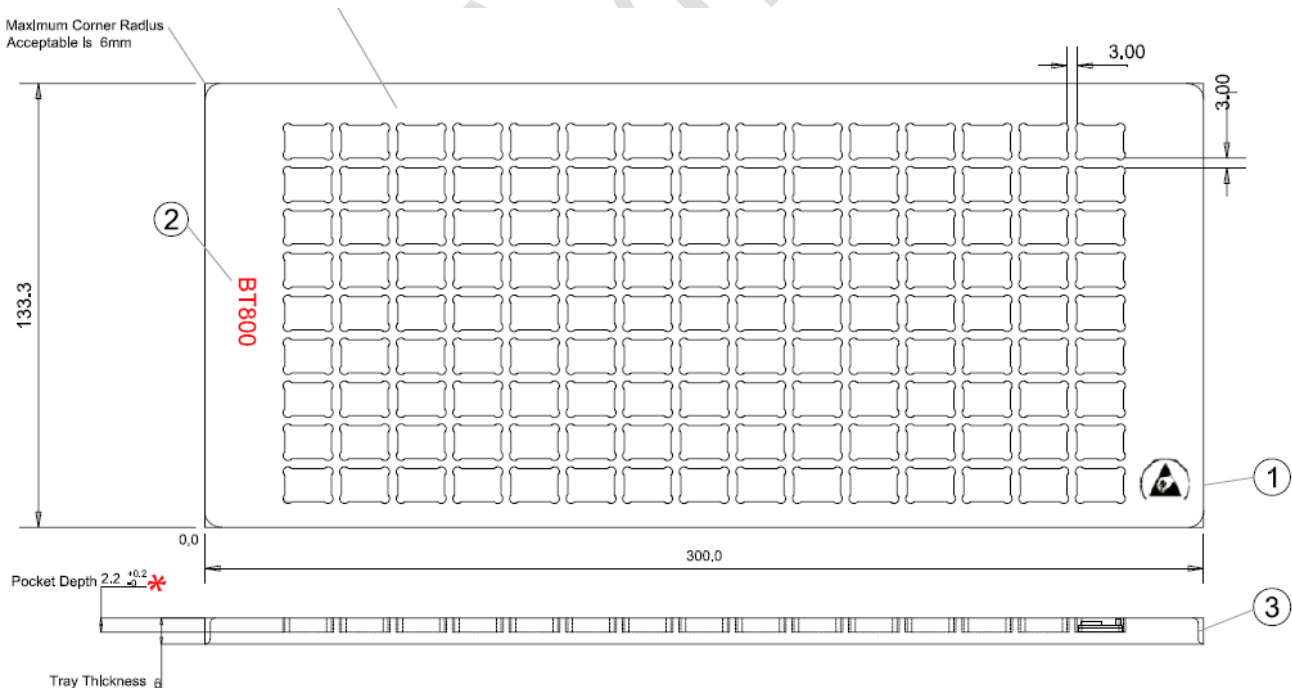


Figure 21: Shipping tray layout

13.3 Reflow Parameters

Laird surface mount modules are designed to be easily manufactured, including reflow soldering to a PCB. Ultimately it is the responsibility of the customer to choose the appropriate solder paste and to ensure oven temperatures during reflow meet the requirements of the solder paste. Laird’s surface mount modules conform to J-STD-020D1 standards for reflow temperatures.

Important: During reflow, modules should not be above 260° and not for more than 30 seconds.

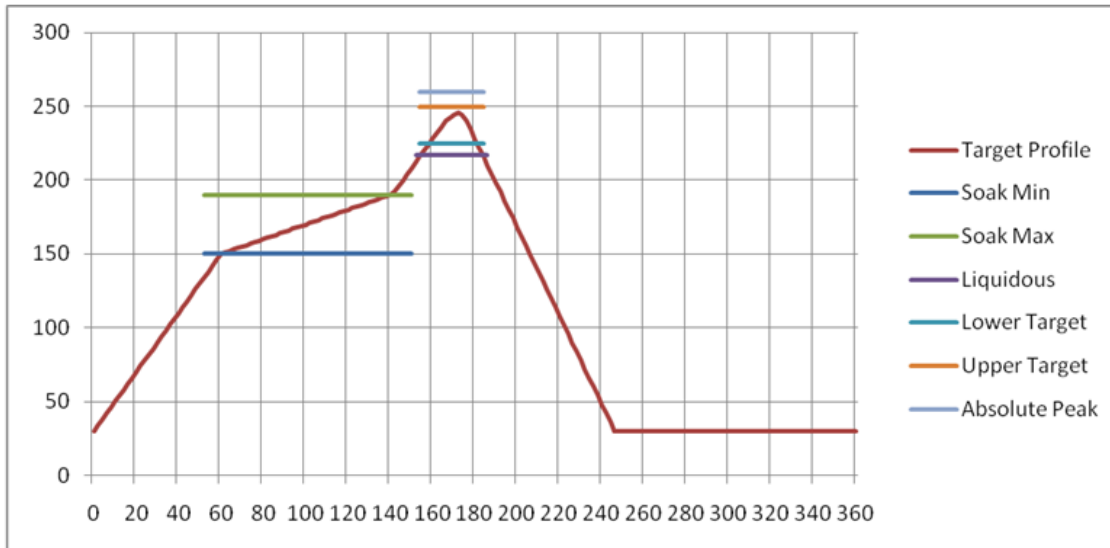


Figure 13-22: Recommended Reflow Temperature

Temperatures should not exceed the minimums or maximums presented in Table 18.

Table 18: Recommended Maximum and minimum temperatures

Specification	Value	Unit
Temperature Inc./Dec. Rate (max)	1~3	°C / Sec
Temperature Decrease rate (goal)	2-4	°C / Sec
Soak Temp Increase rate (goal)	.5 - 1	°C / Sec
Flux Soak Period (Min)	70	Sec
Flux Soak Period (Max)	120	Sec
Flux Soak Temp (Min)	150	°C
Flux Soak Temp (max)	190	°C
Time Above Liquidous (max)	70	Sec
Time Above Liquidous (min)	50	Sec
Time In Target Reflow Range (goal)	30	Sec
Time At Absolute Peak (max)	5	Sec
Liquidous Temperature (SAC305)	218	°C
Lower Target Reflow Temperature	240	°C
Upper Target Reflow Temperature	250	°C
Absolute Peak Temperature	260	°C

14 FCC AND IC REGULATORY

Model	US/FCC	CANADA/IC
BT830	TBC	TBC
BT830	TBC	TBC
DVK-BT830	TBC	TBC

The BT830 family has been designed to operate with the antenna listed below having a maximum gain of 0.5 dBi. The required antenna impedance is 50 ohms.

Item	Part Number	Mfg.	Type	Gain (dBi)
1	AT3216-B2R7HAA	ACX	Ceramic	0.5

14.1 Documentation Requirements

In order to ensure regulatory compliance, when integrating the BT830 into a host device, it is necessary to meet the documentation requirements set forth by the applicable regulatory agencies. The following sections (FCC, Industry Canada, and European Union) outline the information that may be included in the user's guide and external labels for the host devices into which the BT830 is integrated.

FCC

Note: You must place "Contains FCC ID: TBC" on the host product in such a location that it can be seen by an operator at the time of purchase.

User's Guide Requirements

The BT830 complies with FCC Part 15 Rules for a Modular Approval. To leverage Laird's grant, the conditions below must be met for the host device into which the BT830 is integrated:

- The transmitter module is not co-located with any other transmitter or antenna that is capable of simultaneous operation.

As long as the conditions above are met, further transmitter testing is typically not required. However, the OEM integrator is still responsible for testing its end-product for any additional compliance requirements required with this module installed, such as (but not limited to) digital device emissions and PC peripheral requirements.

IMPORTANT:

In the event that the conditions above cannot be met (for example certain device configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

When using Laird's FCC grant for the BT830, the integrator must include specific information in the user's guide for the device into which the BT830 is integrated. The integrator must not provide information to the end user regarding how to install or remove this RF module in the user's manual of the device into which the BT830 is integrated. The following FCC statements must be added in their entirety and without modification into a prominent place in the user's guide for the device into which the BT830 is integrated:

IMPORTANT NOTE: To comply with FCC requirements, the BT830 must not be co-located or operating in conjunction with any other antenna or transmitter.

Federal Communication Commission Interference Statement

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

1. Reorient or relocate the receiving antenna.
2. Increase the separation between the equipment and receiver.
3. Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
4. Consult the dealer or an experienced radio/TV technician for help.

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

IMPORTANT NOTE: FCC Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment.

Industry Canada

Note: You must place "Contains IC ID: TBC" on the host product in such a location that it can be seen by an operator at the time of purchase.

RF Radiation Hazard Warning

Using higher gain antennas and types of antennas not certified for use with this product is not allowed. The device shall not be co-located with another transmitter.

Cet avertissement de sécurité est conforme aux limites d'exposition définies par la norme CNR-102 at relative aux fréquences radio.

This radio transmitter (Contains IC ID: TBC) has been approved by Industry Canada to operate with the antenna types listed in table above with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Le présent émetteur radio (Contains IC ID: TBC) a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés ci-dessous et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

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Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

15 EUROPEAN UNION REGULATORY

The BT830 has been tested for compliance with relevant standards for the EU market. BT830 module was tested with a 0.5 dBi chip antenna.

The OEM should consult with a qualified test house before entering their device into an EU member country to make sure all regulatory requirements have been met for their complete device.

Reference the Declaration of Conformities listed below for a full list of the standards that the modules were tested to. Test reports are available upon request.

15.1 EU Declarations of Conformity

15.1.1 BT830


Manufacturer:	Laird
Product:	BT830-SA / BT830-ST
EU Directive:	RTTE 1995/5/EC
Conformity Assessment:	Annex IV

Reference standards used for presumption of conformity:

Article Number	Requirement	Reference standard(s)
3.1a	Health and Safety	EN60950-1:2006+A11:2009+A1:2010+A12:2011 EN 301 489-1 V1.9.2 (2011-09) EN 301 489-17 V2.2.1 (2012-09)
3.1b	Protection requirements with respect to electromagnetic compatibility	Emissions: EN55022:2006/A1:2007 (Class B) Immunity: EN61000-4-2:2009 EN61000-4-3:2006/A1:2008/A2:2010
3.2	Means of the efficient use of the radio frequency spectrum	EN 300 328 V1.8.1 (2012-06)

Declaration:

We, Laird, declare under our sole responsibility that the essential radio test suites have been carried out and that the above product to which this declaration relates is in conformity with all the applicable essential requirements of Article 3 of the EU Directive 1999/5/EC, when used for its intended purpose.

Place of Issue:	Laird Saturn House, Mercury Park Wooburn Green HP100HH, United Kingdom tel: +44 (0)1628 858 940 fax: +44 (0)1628 528 382
Date of Issue:	July 2013
Name of Authorized Person:	Andrew Dobbing, Engineering Manager
Signature:	

16 ORDERING INFORMATION

Part Number	Description
BT830-SA	BTv4.0 Dual Mode UART HCI Module with integrated Antenna
BT830-ST	BTv4.0 Dual Mode UART HCI Module
DVK-BT830	Development Kit for BT830 Module

16.1 General Comments

This is a preliminary datasheet. Please check with Laird for the latest information before commencing a design. If in doubt, ask.

17 BLUETOOTH SIG APPROVALS

17.1 Application Note: Subsystem Combinations

This application note covers the procedure for generating a new Declaration ID for a Subsystem combination on the Bluetooth SIG website. In the instance of subsystems, a member can combine two or more subsystems to create a complete Bluetooth End Product solution.

Subsystem listings referenced as an example:

Design Name	Owner	Declaration ID	Link to listing on the SIG website
BT830	Laird	TBC	https://www.bluetooth.org/tpg/QLI_viewQDL.cfm?qid=TBC
Windows 8 (Host Subsystem)	Microsoft Corporation	B012854	https://www.bluetooth.org/tpg/QLI_viewQDL.cfm?qid=12854

Laird Customer Declaration ID Procedure

This procedure assumes that the member is simply combining two subsystems to create a new design, without any modification to the existing, qualified subsystems. This is achieved by using the Listing interface on the Bluetooth SIG website. Figure 23 shows the basic subsystem combination of a controller and host subsystem. The Controller provides the RF/BB/LM and HCI layers, with the Host providing L2CAP, SDP, GAP, RFCOMM/SPP and any other specific protocols and profiles existing in the Host subsystem listing. The design may also include a Profile Subsystem.

The controller provides the RF/BB/LM and HCI layers, with the Host providing L2CAP, SDP, GAP, RFCOMM/SPP and any other specific protocols and profiles existing in the Host subsystem listing. The design may also include a Profile Subsystem.

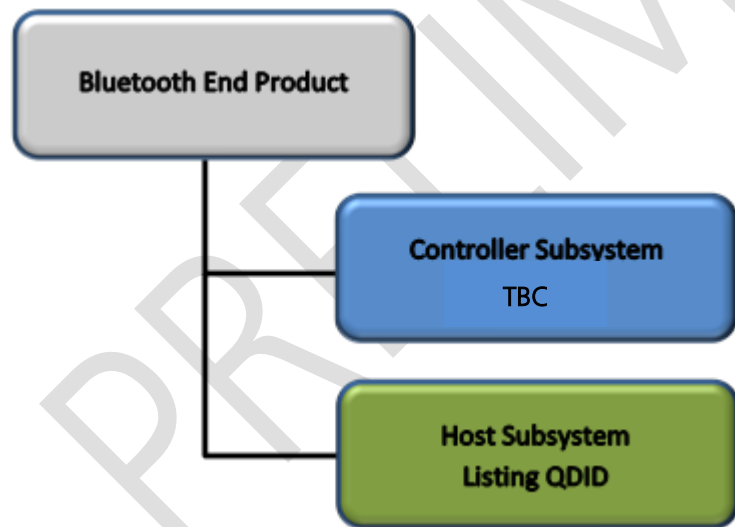


Figure 23: Basic subsystem combination of a controller and host subsystem

The Qualification Process requires each company to registered as a member of the Bluetooth SIG – <http://www.bluetooth.org>

The following link provides a link to the Bluetooth Registration page: <https://www.bluetooth.org/login/register/>

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For each Bluetooth Design it is necessary to purchase a Declaration ID. This can be done before starting the new qualification, either through invoicing or credit card payment. The fees for the Declaration ID will depend on your membership status, please refer to the following webpage:

<https://www.bluetooth.org/en-us/test-qualification/qualification-overview/fees>

For a detailed procedure of how to obtain a new Declaration ID for your design, please refer to the following SIG document:

https://www.bluetooth.org/DocMan/handlers/DownloadDoc.ashx?doc_id=283698&vId=317486

To start the listing, go to: https://www.bluetooth.org/tpg/QLI_SDoc.cfm.

In step 1, select the option, **Reference a Qualified Design** and enter the Declaration IDs of each subsystem used in the End Product design. You can then select your pre-paid Declaration ID from the drop down menu or go to the Purchase Declaration ID page, (please note that unless the Declaration ID is pre-paid or purchased with a credit card, it will not be possible to proceed until the SIG invoice is paid.

Once all the relevant sections of step 1 are finished, complete steps 2, 3, and 4 as described in the help document. Your new Design will be listed on the SIG website and you can print your Certificate and DoC.

For further information please refer to the following training material:

<https://www.bluetooth.org/en-us/test-qualification/qualification-overview/listing-process-updates>

17.2 Additional Assistance

Please contact your local sales representative or our support team for further assistance:

Laird Technologies Connectivity Products Business Unit

Support Centre: <http://ews-support.lairdtech.com>

Email: wireless.support@lairdtech.com

Phone: Americas: +1-800-492-2320 Option 2

Europe: +44-1628-858-940

Hong Kong: +852 2923 0610

Web: <http://www.lairdtech.com/bluetooth>

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Limited Warranty, Disclaimer, Limitation of Liability

PRELIMINARY

Federal Communication Commission Interference Statement

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

IMPORTANT NOTE:

FCC Radiation Exposure Statement:

The product comply with the US portable RF exposure limit set forth for an uncontrolled environment and are safe for intended operation as described in this manual. The further RF exposure reduction can be achieved if the product can be kept as far as possible from the user body or set the device to lower output power if such function is available.

This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

This device is intended only for OEM integrators under the following conditions:

- 1) The transmitter module may not be co-located with any other transmitter or antenna,

As long as 1 condition above is met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed

IMPORTANT NOTE

In the event that these conditions can not be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID can not be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

End Product Labeling

The final end product must be labeled in a visible area with the following: "Contains **FCC ID: SQGBT830**"

Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as show in this manual.

Industry Canada statement:

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions:

- (1) this device may not cause interference, and
- (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

- (1) l'appareil ne doit pas produire de brouillage, et*
- (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.*

Radiation Exposure Statement:

The product comply with the Canada portable RF exposure limit set forth for an uncontrolled environment and are safe for intended operation as described in this manual. The further RF exposure reduction can be achieved if the product can be kept as far as possible from the user body or set the device to lower output power if such function is available.

Déclaration d'exposition aux radiations:

Le produit est conforme aux limites d'exposition pour les appareils portables RF pour les Etats-Unis et le Canada établies pour un environnement non contrôlé. Le produit est sûr pour un fonctionnement tel que décrit dans ce manuel. La réduction aux expositions RF peut être augmentée si l'appareil peut être conservé aussi loin que possible du corps de l'utilisateur ou que le dispositif est réglé sur la puissance de sortie la plus faible si une telle fonction est disponible.

This device is intended only for OEM integrators under the following conditions:

1) The transmitter module may not be co-located with any other transmitter or antenna.

As long as 1 condition above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Cet appareil est conçu uniquement pour les intégrateurs OEM dans les conditions suivantes:

1) Le module émetteur peut ne pas être coïmplanté avec un autre émetteur ou antenne.

Tant que les 1 condition ci-dessus sont remplies, des essais supplémentaires sur l'émetteur ne seront pas nécessaires. Toutefois, l'intégrateur OEM est toujours responsable des essais sur son produit final pour toutes exigences de conformité supplémentaires requis pour ce module installé.

IMPORTANT NOTE:

In the event that these conditions can not be met (for example certain laptop configurations or co-location with another transmitter), then the Canada authorization is no longer considered valid and the IC ID can not be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate Canada authorization.

NOTE IMPORTANTE:

Dans le cas où ces conditions ne peuvent être satisfaites (par exemple pour certaines configurations d'ordinateur portable ou de certaines co-localisation avec un autre émetteur), l'autorisation du Canada n'est plus considéré comme valide et l'ID IC ne peut pas être utilisé sur le produit final. Dans ces circonstances, l'intégrateur OEM sera chargé de réévaluer le produit final (y compris l'émetteur) et l'obtention d'une autorisation distincte au Canada.

End Product Labeling

The final end product must be labeled in a visible area with the following: "Contains IC: 3147A-BT830".

Plaque signalétique du produit final

Le produit final doit être étiqueté dans un endroit visible avec l'inscription suivante: "Contient des IC: 3147A-BT830".

Manual Information to the End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The end user manual shall include all required regulatory information/warning as show in this manual.

Manuel d'information à l'utilisateur final

L'intégrateur OEM doit être conscient de ne pas fournir des informations à l'utilisateur final quant à la façon d'installer ou de supprimer ce module RF dans le manuel de l'utilisateur du produit final qui intègre ce module.

Le manuel de l'utilisateur final doit inclure toutes les informations réglementaires requises et avertissements comme indiqué dans ce manuel.

(For transmitters equipped with detachable antennas)

This radio transmitter (identify the device by certification number, or model number if Category II) has been approved by Industry Canada to operate with the antenna types listed below with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Le présent émetteur radio (IC:3147A-BT830) a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés ci-dessous et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

Type	Manufacture	Gain	Connector
Chip	ACX (Advanced Ceramic X Corp.)	0.5dBi	N/A
Dipole	Nearson	2.0 dBi	IPEX u.FL
PCB Dipole	Laird Technologies	2.0 dBi	IPEX u.FL
Dipole	Laird Technologies	2.0 dBi	IPEX u.FL
Dipole	Laird Technologies	1.5 dBi	IPEX u.FL